

Lead-free alloy chart

Name	Composition	M.P.	Features	Cored Wire	Paste	Bar	Solid
LFM-14	Sn-3.5Ag-0.7Cu	217-218°C	SAC	○	○	×	×
LFM-22(S)	Sn-0.7Cu-(0.04Fe)	227°C (228°C)	Sn-Cu Eutectic	○	×	○	○
LFM-31	Sn-8.0Zn-3.0Bi	190-203°C	Sn-Zn	×	○	×	×
LFM-34	Sn-3.5Ag	221°C	Sn-Ag Eutectic	△	△	×	×
LFM-41(S)	Sn-0.3Ag-2.0Cu-(0.04Fe)	217-270°C (271°C)	Minimize Cu leaching	○	×	○	○
LFM-48(S)	Sn-3.0Ag-0.5Cu-(0.04Fe)	217-220°C (221°C)	SAC, JEITA recommend	○	○	△	△
LFM-52	Sn-3.5Ag-0.5Cu-3.0In	207-214°C	Lower M.P., SABI	×	○	×	×
LFM-59	Sn-3.0Cu	227-312°C	Minimize Cu leaching	×	×	○	○
LFM-62	Sn-3.0Cu-0.5Ni	228-394°C	Minimize Cu leaching	×	×	○	○
LFM-65	Sn-58.0Bi	139°C	Lower M.P., Sn-Bi	×	○	×	×
LFM-70	Sn-3.5Ag-0.5Bi-8.0In	194-206°C	Lower M.P., SABI	×	○	×	×
LFM-71	Sn-3.5Ag-0.5Bi-4.0In	205-212°C	Lower M.P., SABI	×	○	×	×
LFM-73	Sn-1.0Ag-0.5Cu	217-226°C	Low Ag, SAC	△	○	△	△
LFM-74	Sn-10.0Sb	246-258°C	Higher M.P., Sn-Sb	△	○	△	△
LFM-82	Sn-3.9Ag-0.7Cu	217-218°C	SAC	×	△	△	△
LFM-86(S)	Sn-0.3Ag-0.7Cu-(0.04Fe)	217-227°C (228°C)	Low Ag, SAC	△	○	△	△
SJM-03(S)	Sn-0.3Ag-0.7Cu-2.0Bi-0.035Fe	210-226°C	Low Ag, high solder joint strength	○	○	×	×
SJM-10(S)	Sn-1.0Ag-0.7Cu-2.0Bi-0.035Fe	212-224°C	Low Ag, high solder joint strength	○	○	×	×
SJM-30	Sn-3.0Ag-2.0Bi-1.0Sb	216-224°C	High solder joint strength	○	○	×	×
SJM-35	Sn-3.5Ag-2.0Bi	216-220°C	High Ag, high solder joint strength	○	○	×	×

○: Stock item, △: Available, ×: Not available